

AP9990GR-HF-VB Datasheet

N-Channel 60 V (D-S) MOSFET

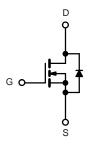
PRODUCT SUMMARY			
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	
60	0.003 at V _{GS} = 10 V	210	
	0.005 at V _{GS} = 4.5 V	185	

FEATURES

- 175 °C Junction Temperature
- TrenchFET® Power MOSFET
- Material categorization:







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_C =	25 °C, unless othe	rwise noted)		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V _{GS}	± 20	V
Continuous Brain Commant (T., 475 90)b	T _C = 25 °C	I-	210	
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 100 °C	I _D	185 ^a	
Pulsed Drain Current		I _{DM}	200	Α
Continuous Source Current (Diode Conduction)		I _S	180 ^a	1
Avalanche Current		I _{AS}	70	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	125	mJ
Mariana Barra Birataria	T _C = 25 °C	В	136	10/
Maximum Power Dissipation	T _A = 25 °C	P _D	3 ^b , 8.3 ^{b, c}	W
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	R_{thJA}	15	18	°C/W
Waximum Junction-to-Ambient	Steady State		40	50	
Maximum Junction-to-Case		R_{thJC}	0.85	1.1	

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. $t \le 10 \text{ s}$.

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SPECIFICATIONS ($T_J = 25$	°C, unless o	otherwise noted)					
Parameter	Symbol	Test Conditions	Min.	Typ.a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 60 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$			250		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	60			Α	
		V _{GS} = 10 V, I _D = 20 A		0.003			
	P	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008			
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010		Ω	
		V _{GS} = 4.5 V, I _D = 15 A		0.005			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S	
Dynamic							
Input Capacitance	C _{iss}			2650			
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		470		pF	
Reverse Transfer Capacitance	C _{rss}			225			
Total Gate Charge ^c	Q_g			47	70		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC	
Gate-Drain Charge ^c	Q_{gd}			12			
Turn-On Delay Time ^c	t _{d(on)}			10	20		
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, R_L = 0.6 \Omega$ $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		15	25	ns	
Turn-Off Delay Time ^c	t _{d(off)}			35	50		
Fall Time ^c	t _f			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)					
Pulsed Current	I _{SM}				60	Α	
Diode Forward Voltage	V_{SD}	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		45	100	ns	

Notes:

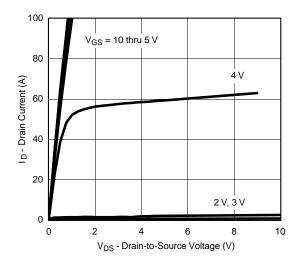
- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

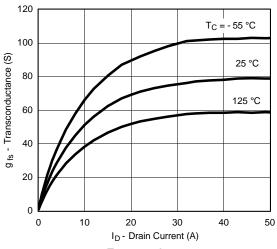
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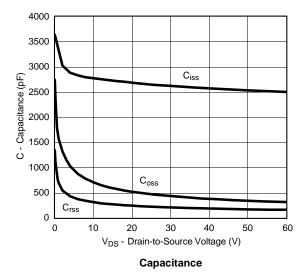
TYPICAL CHARACTERISTICS (25 °C unless noted)

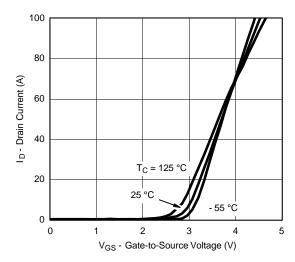


Output Characteristics

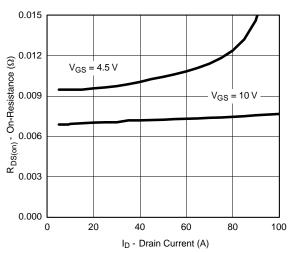


Transconductance

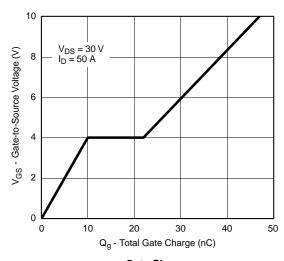




Transfer Characteristics



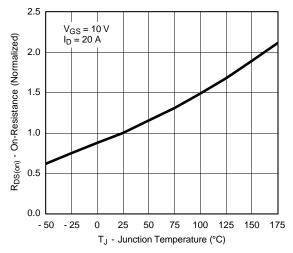
On-Resistance vs. Drain Current



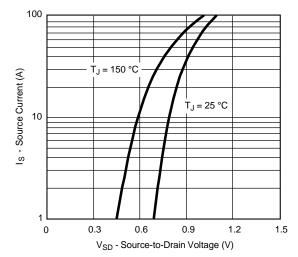
Gate Charge



TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

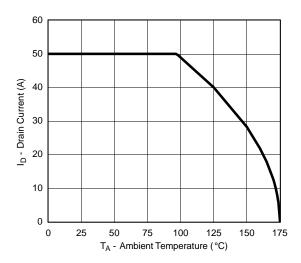


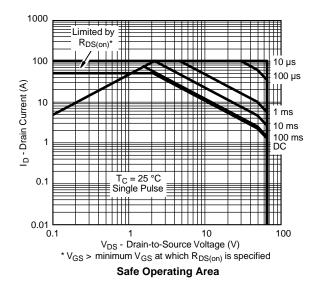
Source-Drain Diode Forward Voltage

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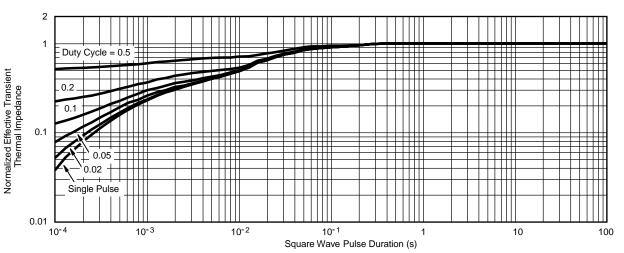


THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



Normalized Thermal Transient Impedance, Junction-to-Case

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